ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan	C. Bannock	burn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration en	on of the su	bstances w all lower	vithin the manufactu level materials for w	rer listed i hich the n	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Fo http://www.ipc.org/IPC-175x Di				 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material 				ials and M	uls and Mfg Information				
upplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Respons	Response Date*			
nsemi										2024-04	2024-04-20			
ontact Name	Title - Contact					Phone - Contact*				Email -	Email - Contact*			
roduct-Env-Stewards Product Enviro			iro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represe			entative		Phone - Representative*			Email - Representative*						
Product-Env-Stewards Pro-			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	anufacturing Site	,	Weight*	UOM	Unit Type	
	AP0100 A0-DR	AP0100AT2L00XUG 1 MP Co-Proces		sor		2024-04-20		М	MY5		89.81	mg	Each	
Ianufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Ma	terial	rial Terminal Base Alloy		J-STD-020 MSL Rating		Peak Proce	Process Body Temperature		re Max Time at Peak Tempera		ure Num	ber of Reflow Cyc	les	
SnAgCu CU Alloy		CU Alloy	3			260 C 30		seconds 3						
omments														
TTENTION: MSL 3 Rated item requires	Bake and I	Dry Pack (after	electrical test)											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.61	mg		Misc.	proprietary data		0.0192	mg
			Supplier	Silicon (Si)	7440-21-3		6.5842	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0066	mg
Die Attach	0.66	mg	Supplier	Epoxy resins	129915-35-1		0.0627	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.1947	mg
			Supplier	Acrylic resins	Proprietary Data		0.0957	mg
			Supplier	Polyimide	Proprietary Data		0.1947	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.1122	mg
Mold Compound-Black	43.67	mg		Phenolic Resin	proprietary data		2.0743	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		2.1835	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1092	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.303	mg
Solder Ball	10.46	mg	Supplier	Silver (Ag)	7440-22-4		0.3138	mg
			Supplier	Tin (Sn)	7440-31-5		10.0939	mg
			Supplier	Copper (Cu)	7440-50-8		0.0523	mg
Substrate and Solder Mask	27.33	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		5.7912	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		0.358	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0875	mg
			Supplier	Acetophenone Derivative	Proprietary Data		0.5357	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0902	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8		0.0902	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		3.5748	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.0713	mg
			Supplier	Copper (Cu)	7440-50-8		12.9599	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.7713	mg
Wire Bond - Au	1.08	mg	Supplier	Gold (Au)	7440-57-5		1.08	mg